

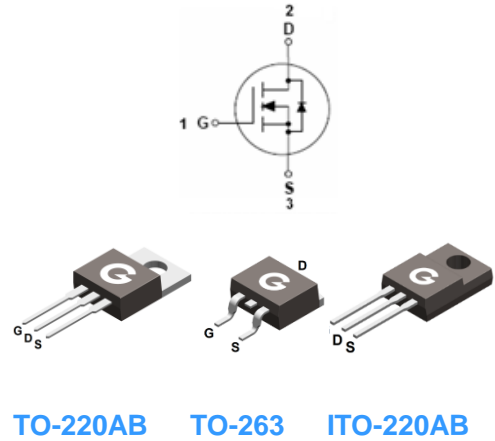
### Features

- Fast switching
- Low gate charge
- Low reverse transfer capacitances
- RoHS compliant with Halogen-free

HF

### Mechanical Data

- Case: TO-220AB, TO-263, ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL4N80	TO-220AB	50 pcs / Tube	4N80
BL4N80B	TO-263	50 pcs / Tube or 800 pcs / Tape & Reel	4N80B
BL4N80F	ITO-220AB	50 pcs / Tube	4N80F

### Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	800	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current ( $T_C = 25^\circ\text{C}$ )	$I_D$	4	A
Continuous Drain Current ( $T_C = 100^\circ\text{C}$ )		3.2	A
Pulsed Drain Current	$I_{DM}$	16	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	120	mJ
Power Dissipation (TO-220AB, $T_C = 25^\circ\text{C}$ )	$P_D$	110	W
Power Dissipation (TO-263, $T_C = 25^\circ\text{C}$ )		110	W
Power Dissipation (ITO-220AB, $T_C = 25^\circ\text{C}$ )		45	W
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	TO-220AB/TO-263	ITO-220AB	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	1.14	2.78	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	50	62.5	$^\circ\text{C/W}$

### Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$V_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	800	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 800V, V_{GS} = 0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$R_{DS(ON)}$	Drain-Source On-resistance *1	$V_{GS} = 10V, I_D = 2A$	-	-	4.2	$\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	-	4	V
<b>Dynamic Characteristics</b>						
$C_{ISS}$	Input Capacitance	$V_{GS} = 0V$	-	1350	-	pF
$C_{OSS}$	Output Capacitance	$V_{DS} = 25V$	-	100	-	
$C_{RSS}$	Reverse Transfer Capacitance	$f = 1.0\text{MHz}$	-	15	-	
<b>Switching Characteristics</b>						
$t_{d(ON)}$	Turn-on Delay Time *3	$V_{DD} = 400V$	-	16	-	ns
$t_r$	Turn-on Rise Time *3	$V_{GS} = 10V$	-	18	-	
$t_{d(OFF)}$	Turn-Off Delay Time *3	$I_D = 4A$	-	50	-	
$t_f$	Turn-Off Fall Time *3	$R_G = 12\Omega$	-	25	-	
$Q_G$	Total Gate-Charge	$V_{DD} = 400V$	-	35	-	nC
$Q_{GS}$	Gate to Source Charge	$V_{GS} = 10V$	-	10	-	
$Q_{GD}$	Gate to Drain (Miller) Charge	$I_D = 4A$	-	16	-	
<b>Source-Drain Diode Characteristics</b>						
$V_{SD}$	Diode Forward Voltage *1	$I_{SD} = 4A, V_{GS} = 0V$	-	-	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_F = 4A, V_{GS} = 0V$	-	820	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	4.95	-	$\mu C$

Notes:

1. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
2. The  $E_{AS}$  data shows Max. rating. The test condition is  $V_{DD} = 50V, V_{GS} = 15V, L = 10mH$
3. Guaranteed by design, not subject to production

### Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

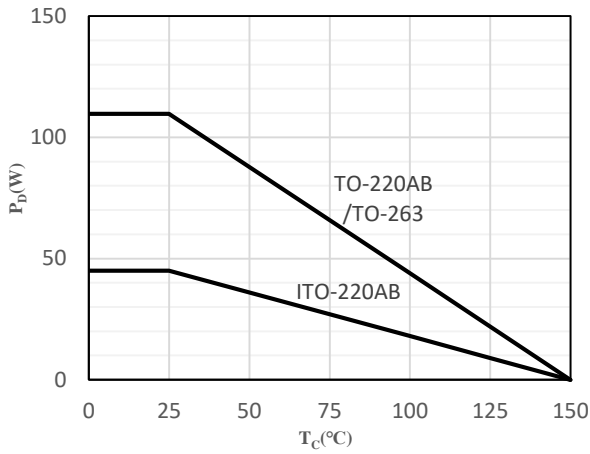


Fig 1 Power Dissipation

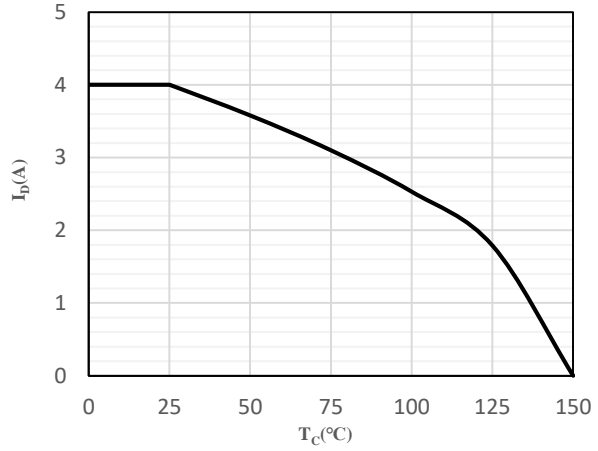


Fig 2 Drain Current

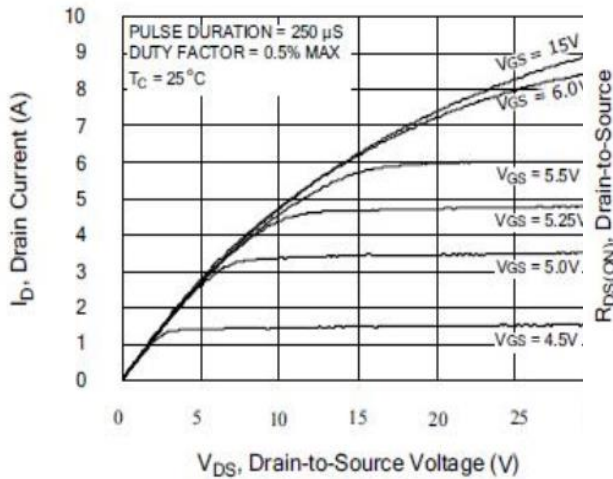


Fig 3 Typical Output Characteristics

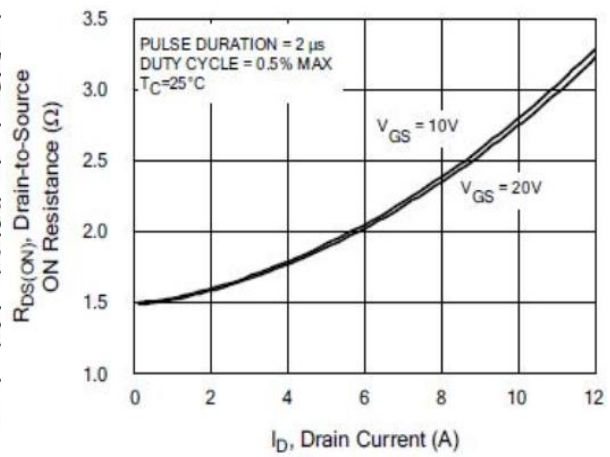


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

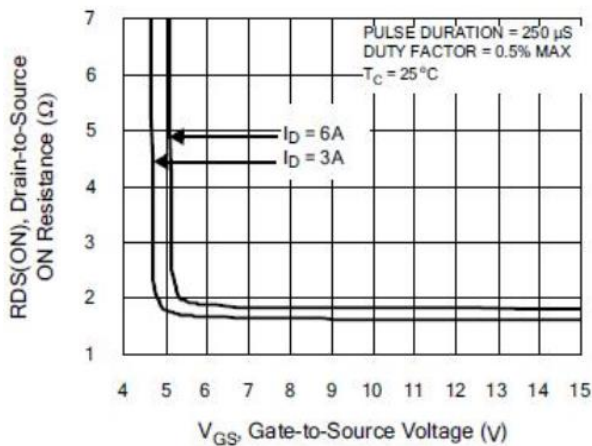


Fig 5 On-Resistance vs. Gate-Source Voltage

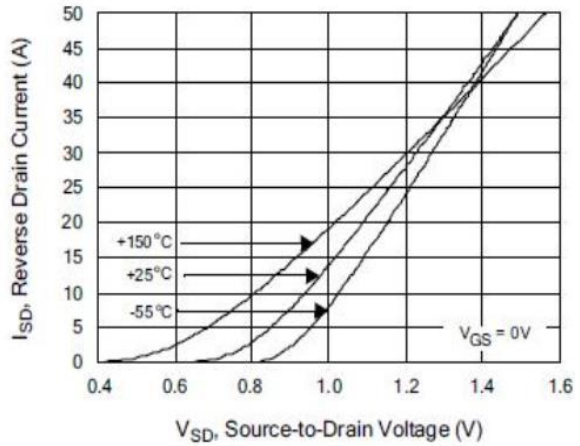
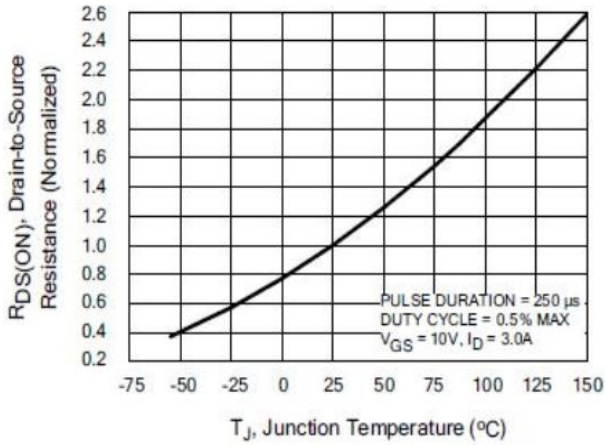
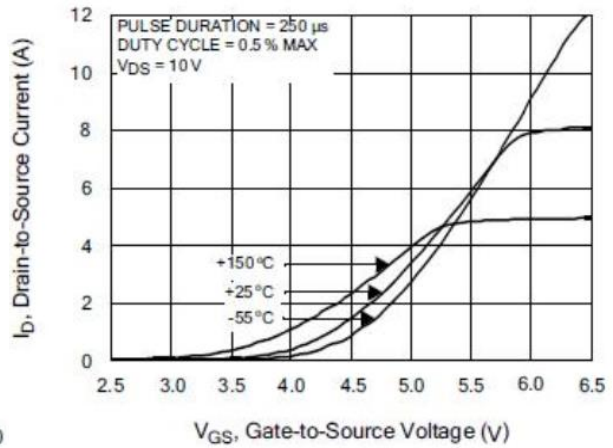


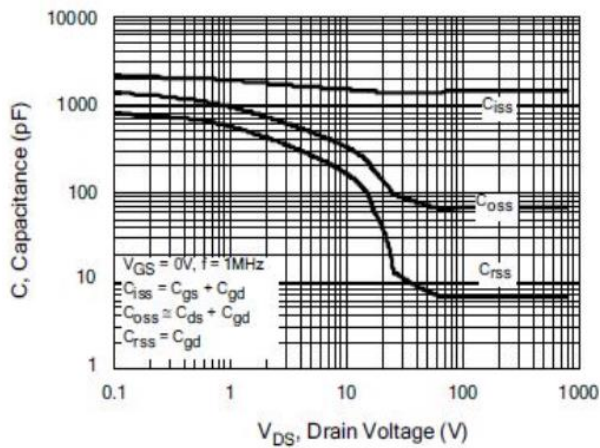
Fig 6 Body-Diode Characteristics



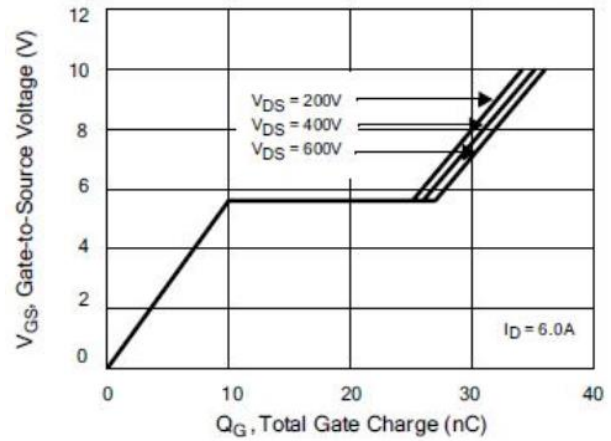
**Fig 7 Normalized On-Resistance vs. Junction Temperature**



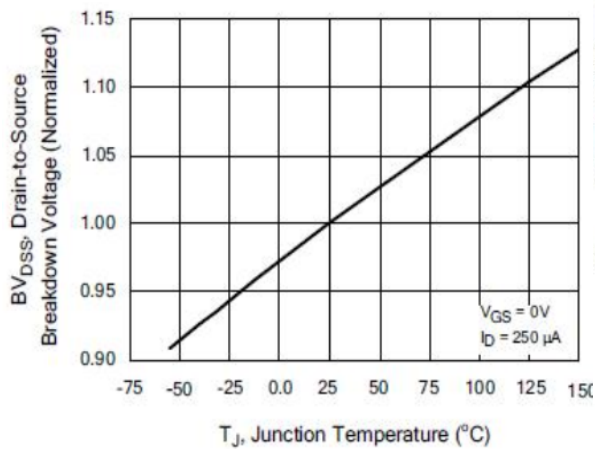
**Fig 8 Transfer Characteristics**



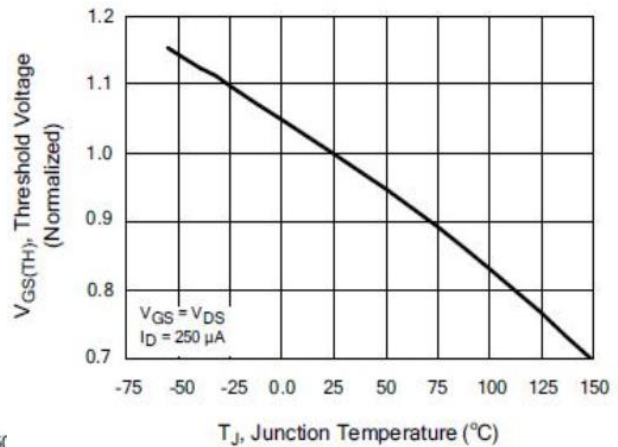
**Fig 9 Capacitance Characteristics**



**Fig 10 Gate-Charge Characteristics**



**Fig 11 Normalized Breakdown Voltage vs. Junction Temperature**



**Fig 12 Normalized V<sub>GS(th)</sub> vs. Junction Temperature**

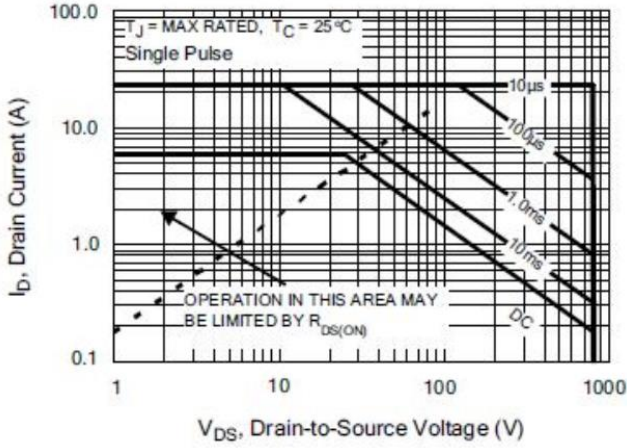


Fig 13 Safe Operating Area (TO-220AB / TO-263)

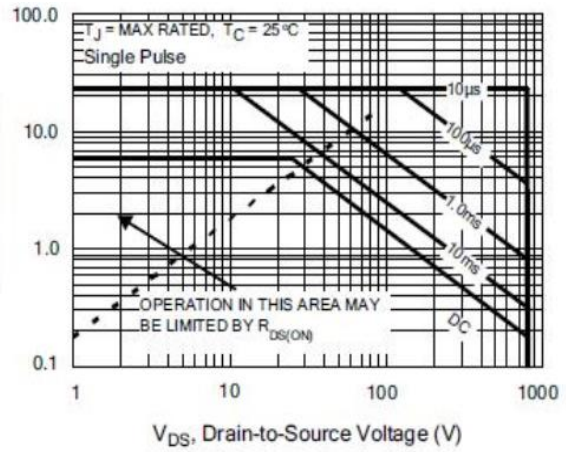


Fig 14 Safe Operating Area (ITO-220AB)

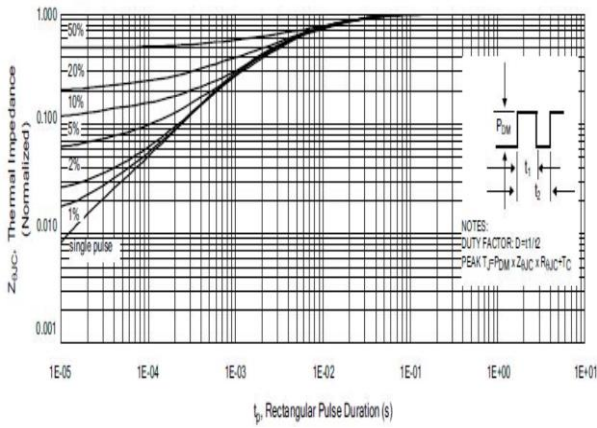


Fig 15 Maximum transient thermal impedance  
(TO-220AB / TO-263)

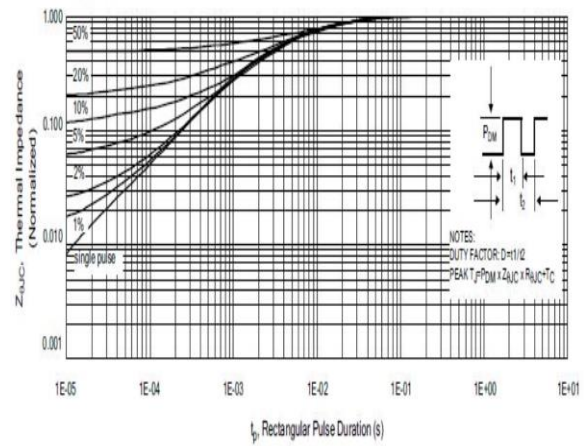
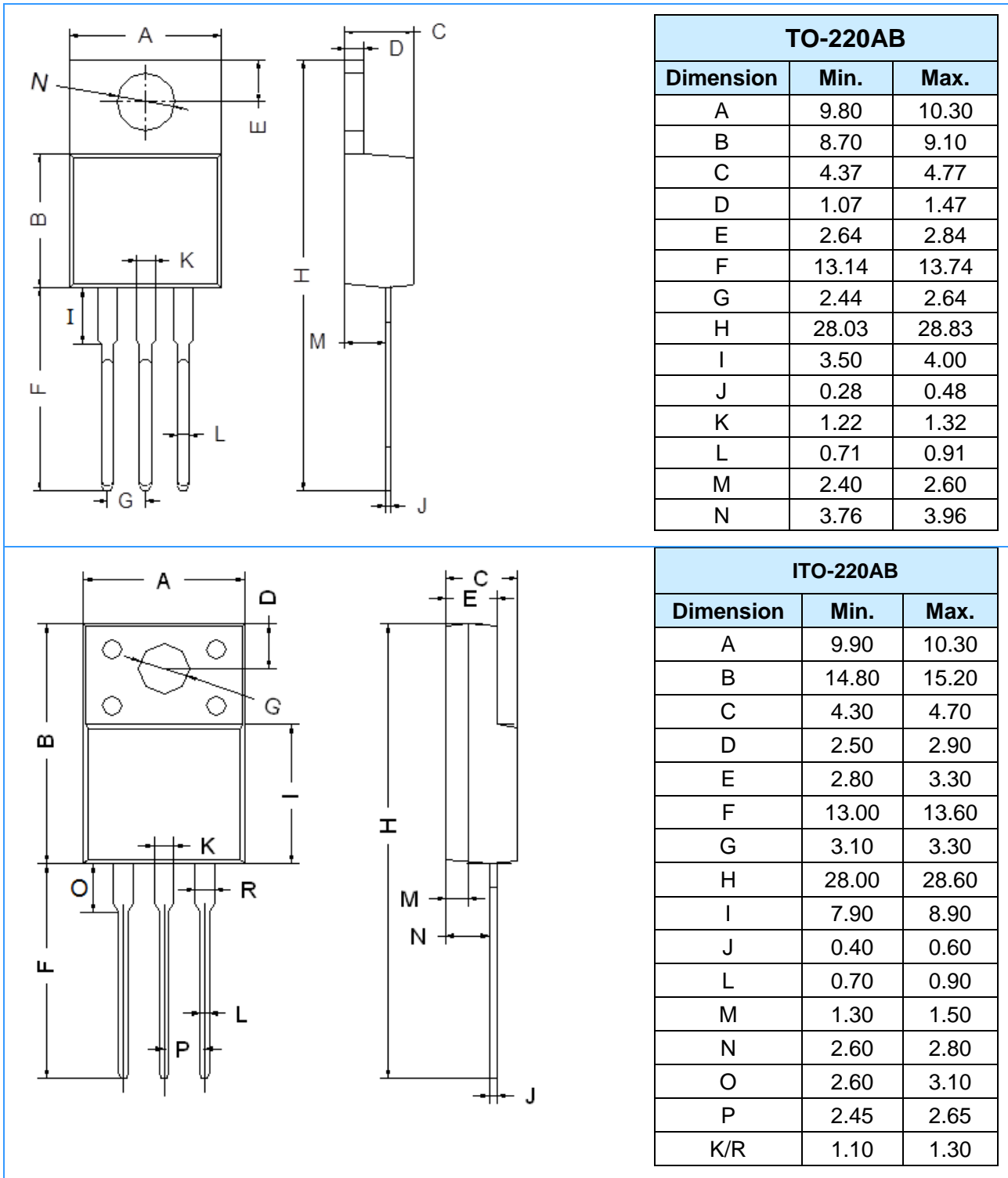
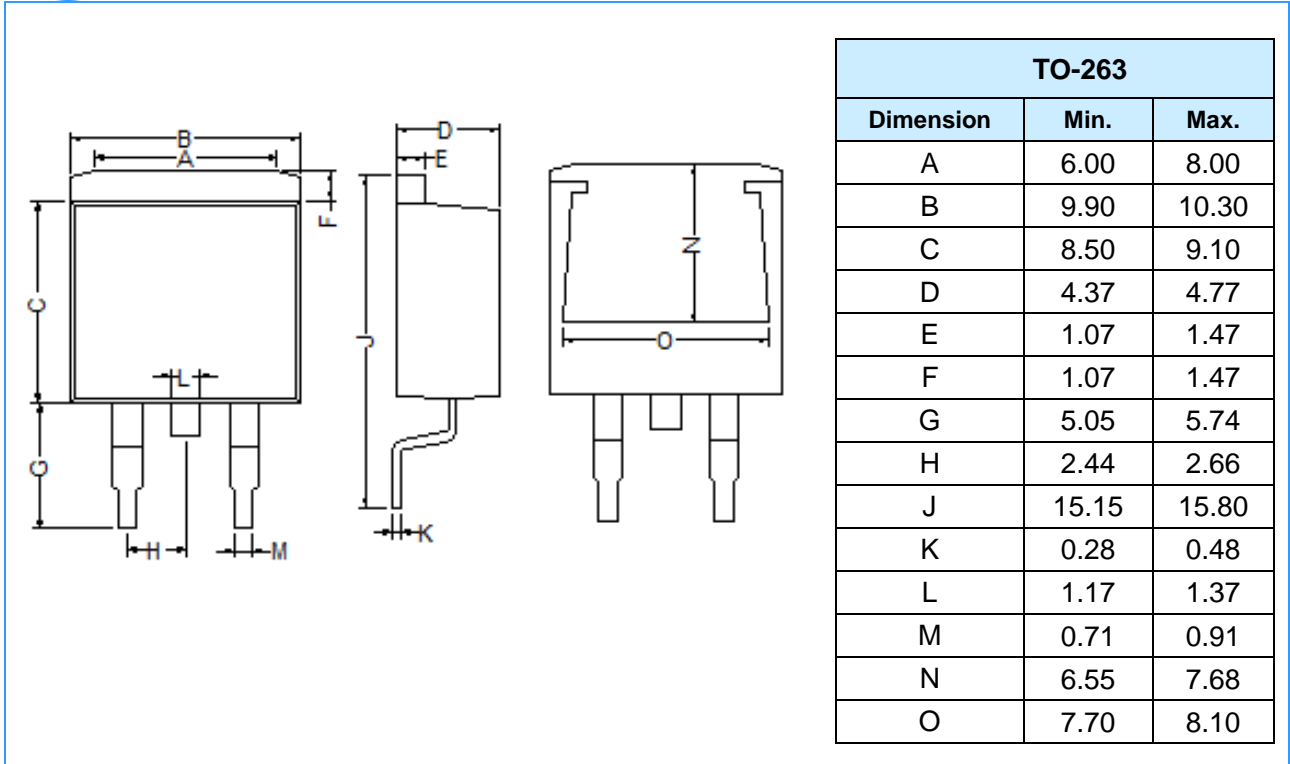


Fig 16 Maximum transient thermal impedance  
(ITO-220AB)

### Package Outline Dimensions (Unit: mm)





**Mounting Pad Layout** (Unit: mm)

